

AMENDMENTS TO THE SPECIFICATION

Please replace the Title of the Invention with the following amended Title of the Invention:

--FILLER MATERIAL AND PRETREATMENT OF A PRINTED ~~PRINTED~~ CIRCUIT BOARD
COMPONENTS TO FACILITATE APPLICATION OF A CONFORMAL EMI SHIELD --

Please replace the paragraph on Page 4, lines 12 to 15 with the following amended paragraph:

Preferably, the filler material is thixotropic. For example, an epoxy such as an epoxy from the family of Bisphenol-A epoxies mixed with an amine hardener ~~hardner~~ can be used. Preferably, the epoxy is a thermally cured epoxy. Alternatively, a latex based non-electrically conductive epoxy can be used.

Please replace the paragraph on Page 32, lines 20 to 27 with the following amended paragraph:

Although the viscosity can vary, filler material 902 is preferably thixotropic, enabling it to be extruded into and over cavities 900 while covering the top, side and other surfaces of components 914. In one embodiment, filler material 902 is an epoxy such as any epoxy from the family of Bisphenol-A epoxies mixed with an amine hardener ~~hardner~~. In one particular embodiment, filler material 902 is an EMCAST, CHIPSHIELD, 3400-2500 and 3600 series epoxies available from Electronic Materials, Inc., Breckenridge, CO. A thermally cured epoxy is preferred due to the inability to directly apply UV radiation to filler material 902 that is disposed in cavities 900 due to shadows cast by the components.